

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1064-7csw#trpbf

(Engineering Calculation)

SOIC WIDE

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TOTAL MASS (g) : 0.254975

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.009084 | 1000000 | 35626.96875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.138021 | 975000 | 541311.125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003397 | 24000 | 13322.8554688 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000042 | 300 | 164.721786499 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000099 | 700 | 388.272766113 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.141559 | 1000000 | 555187 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.004771 | 1000000 | 18713.0546875 | | |
| | | External Plating Total: | | | | 0.004771 | 1000000 | 18713.0546875 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001132 | 1000000 | 4439.64453125 | | |
| Internal Plating Total: | | | | 0.001132 | 1000000 | 4439.64453125 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.002044 | 750000 | 8016.46044922 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000681 | 250000 | 2670.84619141 | | |
| Die Attach Total: | | | | 0.002725 | 1000000 | 10687.3066406 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.009816 | 103000 | 38497.8359375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.085294 | 895000 | 334518.59375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000191 | 2000 | 749.091918945 | | |
| | | Encapsulation Total: | | | | 0.095301 | 1000000 | 373765.5 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000403 | 1000000 | 1580.54492188 | | |
| | | | | | TOTAL MASS (g) : | 0.254975 | | |